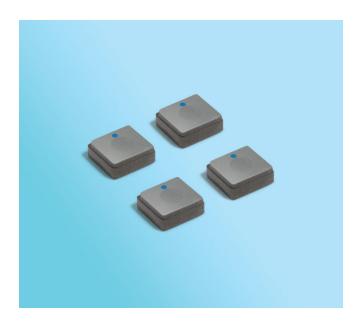
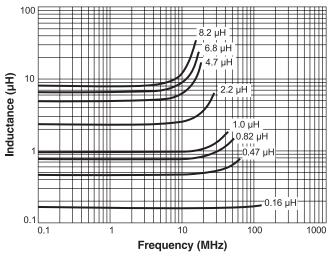
# Outgassing Compliant Power Inductors AE457PGA



## **Typical L vs Frequency**



- High temperature materials allow operation in ambient temperatures up to 155°C
- Passes NASA low outgassing specifications
- Tin-lead (Sn-Pb) termination for the best possible board adhesion
- Exceptionally low DCR; soft saturation
- Passes vibration testing to 80 G and shock testing to 1000 G

Core material Composite

**Terminations** Tin-lead (63/37) over copper. Other terminations available at additional cost.

**Weight:** 0.26 – 0.36 g

Operating voltage: 0-80 V

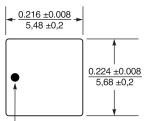
Ambient temperature -55°C to +105°C with Irms current Maximum part temperature +155°C (ambient + temp rise) Storage temperature Component: -55°C to +155°C.

Tape and reel packaging: -55°C to +80°C

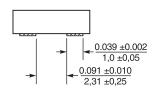
Resistance to soldering heat Max three 40 second reflows at +260°C, parts cooled to room temperature between cycles

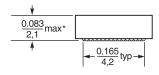
Moisture Sensitivity Level (MSL) 1 (unlimited floor life at <30°C / 85% relative humidity)

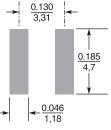
Packaging 250/7" reel; 750/13" reel Plastic tape: 16 mm wide, 0.30 mm thick, 12 mm pocket spacing, 5.21 mm pocket depth PCB washing Tested to MIL-STD-202 Method 215 plus an additional aqueous wash. See Doc787\_PCB\_Washing.pdf.



Indicates direction of terminals and start (short) lead. Connect high dv/dt here for lowest EMI.







\*For optional tin-lead and tin-silver-copper terminations, dimensions are for the mounted part. Dimensions before mounting can be an additional 0.008 inch / 0.2 mm.

Suggested Land Pattern

Dimensions are in inches mm



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## **AE457PGA Shielded Power Inductors**

	Inductance <sup>2</sup> DCR		mOhms)³	SRF (MHz)4		Isat (A) <sup>5</sup>			Irms (A)6	
Part number <sup>1</sup>	±20% (μH)	typ	max	min	typ	10% drop	20% drop	30% drop	20°C rise	40°C rise
AE457PGA161MSZ	0.16	1.8	2.1	120	150	11.5	19.0	27.0	16.1	22.1
AE457PGA331MSZ	0.33	2.7	3.2	72	90	8.3	13.5	18.8	12.9	18.3
AE457PGA471MSZ	0.47	3.7	4.3	60	75	6.4	10.7	15.7	12.0	16.6
AE457PGA561MSZ	0.56	4.2	4.9	56	70	6.3	10.5	15.2	10.5	14.6
AE457PGA681MSZ	0.68	5.3	6.1	52	65	6.2	10.0	14.0	9.7	13.2
AE457PGA821MSZ	0.82	5.9	6.8	44	55	5.0	8.5	12.3	9.3	12.8
AE457PGA901MSZ	0.90	7.0	8.0	40	50	5.0	8.3	11.8	8.6	11.7
AE457PGA102MSZ	1.0	7.5	8.7	40	50	4.9	8.1	11.4	8.3	11.3
AE457PGA122MSZ	1.2	8.9	10.3	32	40	4.3	7.1	10.0	7.5	10.0
AE457PGA152MSZ	1.5	11.4	13.2	30	38	3.7	6.2	8.9	7.1	9.6
AE457PGA182MSZ	1.8	14.3	16.5	28	35	3.7	6.0	8.3	6.5	8.8
AE457PGA222MSZ	2.2	16.3	18.8	24	30	3.3	5.4	7.6	5.9	8.0
AE457PGA332MSZ	3.3	23.4	27.0	20	25	2.8	4.5	6.5	5.1	7.1
AE457PGA472MSZ	4.7	36.0	41.5	16	20	2.2	3.6	5.3	4.3	5.9
AE457PGA562MSZ	5.6	45.1	52.0	15	19	2.1	3.4	4.9	3.2	4.4
AE457PGA682MSZ	6.8	55.0	63.5	14	18	2.0	3.2	4.5	2.7	3.7
AE457PGA822MSZ	8.2	64.0	73.6	13	16	1.8	2.9	4.1	2.5	3.4

1. When ordering, please specify screening code:

#### AE457PGA822MSZ

**Screening: Z** = Unscreened

Y = Unscreened (SLDC Option A)

W = Unscreened (SLDC Option A)

H = Coilcraft CP-SA-10001 Group A

G = Coilcraft CP-SA-10001 Group A (SLDC Option A)

D = Coilcraft CP-SA-10001 Group A (SLDC Option B)

1 = EEE-INST-002 (Family 1) Level 1

2 = EEE-INST-002 (Family 1) Level 2

3 = EEE-INST-002 (Family 1) Level 3

4 = MIL-STD-981 (Family 04) Class B

5 = MIL-STD-981 (Family 04) Class S

**F** = ESCC3201 (F4 operational life performed at 105°C)

· Screening performed to the document's latest revision.

· Lot qualification (Group B) available.

· Custom testing also available.

- 2. Inductance tested at 1 MHz, 0.1 Vrms, 0 Adc.
- 3. DCR measured on a micro-ohmmeter.
- 4. SRF measured using Agilent/HP 4395A or equivalent.
- 5. DC current at 25°C that causes the specified inductance drop from its value without current.

Click for temperature derating information.

- 6. Current that causes the specified temperature rise from 25°C ambient. This information is for reference only and does not represent absolute maximum ratings. Click for temperature derating information.
- 7. Electrical specifications at 25°C.

Refer to Doc 362 "Soldering Surface Mount Components" before soldering.

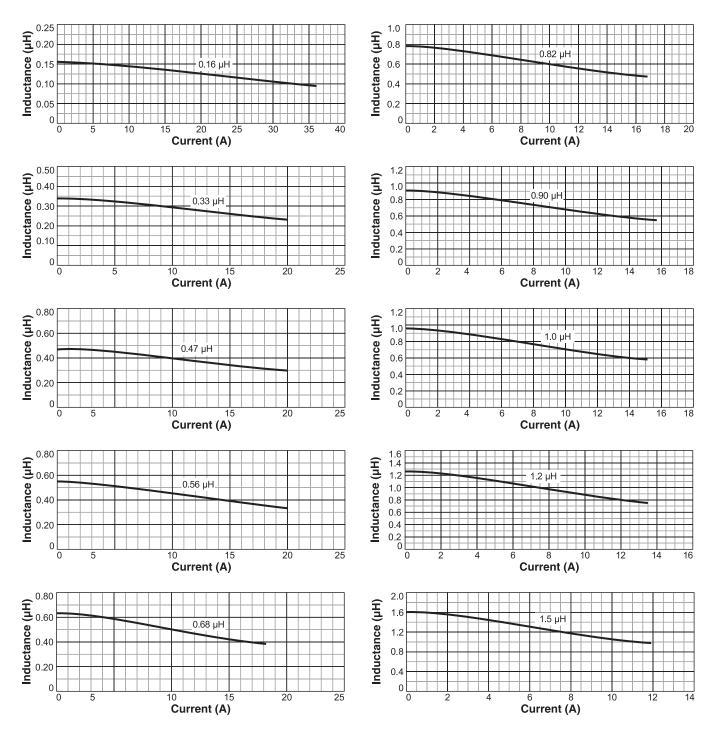
#### **Irms Testing**

Irms testing was performed on a 0.060" inch thick pcb with 4 oz copper traces optimized to minimize additional termperature rise.

Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components. Therefore temperature rise should be verified in application conditions.

# **AE457PGA Shielded Power Inductors**

## L vs Current



# **AE457PGA Shielded Power Inductors**

## L vs Current

